

Atty. Docket No. YOR920040272us1

RECORDATION FORM COVER SHEET **PATENTS ONLY**

To The Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>Huiling Shang Meikei Jeong Jack O. Chu Kathryn W. Guarini</p> <p>Additional name(s) of conveying party(ies) attached? <u>Yes</u> <u>X</u> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: International Business Machines Corporation Address: New Orchard Road Armonk, NY 10504</p> <p>Additional name(s) & addresses attached? <u>Yes</u> <u>X</u> No</p>
<p>3. Nature of conveyance:</p> <p><u>X</u> Assignment</p> <p>Execution Date(s): <u>06/23/2004</u>, <u>06/23/2004</u>, <u>06/23/2004</u>, and <u>06/24/2004</u></p>	<p>4. Patent Application number(s)</p> <p align="center">10/876,155</p> <p>Execution Date(s): <u>07/02/2004</u>, <u>07/02/2004</u>, <u>07/02/2004</u>, and <u>07/02/2004</u></p>
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: George Sai-Halasz Address: 145 Fernwood Drive East Greenwich, RI 02818</p>	<p>6. Total number of applications involved: 1</p> <p>7. Total fee (37 CFR 3.41): \$40.00</p> <p><u>X</u> Charge to Deposit Account No.: <u>50-0510</u></p>
<p align="center">DO NOT USE THIS SPACE</p>	
<p>8. Statement and signature.</p> <p>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of original document.</p> <p>George Sai-Halasz (Reg. No. 45,430) <u>George Sai-Halasz</u> <u>08/30/2004</u> Name of Person Signing Signature Date</p> <p>Total Number of pages including cover sheet, attachments, and document: <u>3</u></p>	
<p align="center">DO NOT DETACH THIS PORTION</p>	
<p>Mail documents to be recorded with required cover sheet information to: Commissioner for Patents Mail Stop Assignments Alexandria, VA 22313-1450</p>	
<p>Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, DC 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, DC 20503.</p>	

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(JOINT FORM)
(FOUR INVENTORS)

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Assignment

Whereas, we

INVENTOR AND CITY	(1) Huiling Shang County of Westchester	of Yorktown Heights and State of New York
INVENTOR AND CITY	(2) Meikei Ieong County of Dutchess	of Wappingers Falls and State of New York
INVENTOR AND CITY	(3) Jack O. Chu County of Nassau	of Manhasset and State of New York
INVENTOR AND CITY	(4) Kathryn W. Guarini County of Westchester	of Yorktown Heights and State of New York

have invented certain improvements in

TITLE Integration of strained Ge into advanced CMOS technology

DATES THAT
INVENTORS
SIGNED THE
DECLARATION

and executed, respectively, a United States nonprovisional patent application therefor on (1) 06/23/2004 and (2) 06/23/2004 and (3) 06/23/2004 and (4) 06/24/2004.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

JUL 06 '04 16:26 FR IBM

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P.03

(JOINT FORM)
(FOUR INVENTORS)Docket YOR920040272US1, Page 2 of 2


Assignment

Integration of strained Ge into advanced CMOS technology


Signed and sealed

CITY AND
DATE(1) at Yorktown Heights
on July 2, 2004
(Huiling Shang)
SIGNATURE
INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME


Signed and sealed

CITY AND
DATE(2) at Yorktown Heights
on July 2, 2004
(Meikei Jeong)
SIGNATURE
INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

Signed and sealed

CITY AND
DATE(3) at Yorktown Heights
on July 2, 2004
(Jack O. Chu)
SIGNATURE
INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME

Signed and sealed

CITY AND
DATE(4) at Yorktown Heights
on July 2, 2004
(Kathryn W. Gaerem)
SIGNATURE
INVENTOR
FIRST NAME MIDDLE INITIAL LAST NAME